

ABSTRACT OF THE DISCLOSURE

An apparatus for controlling the temperature of an electronic device utilizes a thermal head attached to a base structure including an integral isolation arrangement. For example, the isolation arrangement can be formed as a planar spring defined by slots in the base structure. The base structure has a manifold configured to route refrigerant fluid between the thermal head and components of a refrigeration system. The isolation arrangement is normally planar but is movable to facilitate engagement of the thermal head with the electronic device. The isolation arrangement also compensates for variations in the planar orientation of the electronic device.